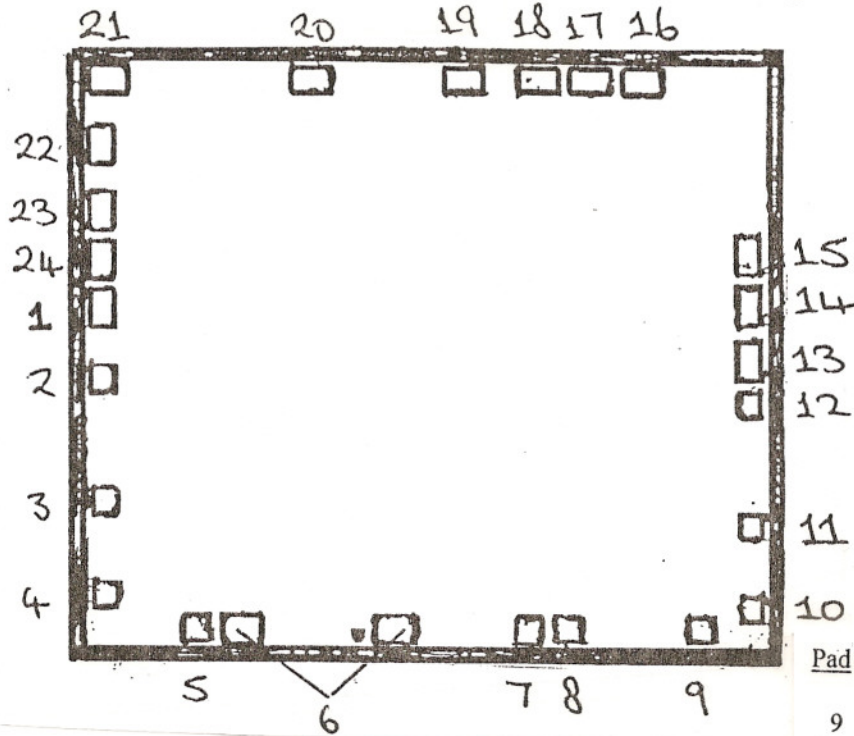




Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pad	Function
1	BHB
2	BHI
3	BLI
4	ALI
5	AHI
6	V _{ss} (2bond pads)
7	RDEL
8	UVLO

Pad	Function	Pad	Function
9	RFSH	17	AHO
10	DIS	18	AHS
11	CLI	19	CLO
12	CHI	20	V _{DD}
13	CHB	21	ALO
14	CHO	22	BLO
15	CHS	23	BHS
16	AHB	24	BHO

Topside Metal: Al
Backside: Si
Backside Potential:
Mask Ref: Issue 1
Bond Pads : .003 min

APPROVED BY: CB
MFG: Harris

DIE SIZE: .108" x .068"
THICKNESS: .020"

DATE: 2/6/01
P/N: HIP4082

DG 10.1.2
 Rev A 3-4-99